**UNIQUE AND INNOVATIVE PHOTONIC SOLUTIONS**

**FREEDOM PHOTONICS** is a manufacturer of unique and innovative photonic components, modules and subsystems. Our advanced semiconductor and dielectric photonic integration technology platforms are enabling new, high-performance fiber and free-space optical communication and sensing systems aimed at applications in diverse markets. If one of our standard products do not work for you, and you have a need that can be met through customizing our core photonic technology in Indium Phosphide, Gallium Arsenide or Silicon, we will be happy to provide a private label solution to support your needs.

**Product Families**
- Fast tunable lasers from 1250nm to 1750nm
- Swept tunable laser sources
- High power lasers: single and multi-mode, tunable – 780nm to 1700nm
- Optical transmitters (fiber and free-space)
- High power photodetectors for RF photonics

**Private Label Photonic Integrated Circuits (InP, GaAs, Silicon, Dielectric)**
- Private label product building blocks (InP, GaAs, Si)
  - Active and passive waveguide components
  - Widely tunable lasers and high-power single mode lasers
  - High-speed modulators
  - High-power and speed photodetectors
  - Micro-optic assemblies
  - Hermetic optical modules
  - Controllers and fully integrated systems

41 Aero Camino, Santa Barbara, CA 93117, 805-967-4900, freedomphotonics.com
### PRIVATE LABEL PRODUCTS

Our team’s world class expertise in vertically integrated photonic product design (device-module-system) and production has helped many customers prove feasibility, develop, and deploy new products for a variety of applications. Let us help you be successful by providing a complete design to manufacturing solution for your market needs. Focus on what you know best and leave the photonics piece to us.

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